

paragraphs individually numbered. The clean form of the substitute specification is attached hereto in Exhibit B.

2. In the Claims

Please amend claims 1, 6 and 11 as follows. A marked up version of the amended claims is attached hereto.

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1. (Amended) A solder comprising:
from 88.5% to 93.2% tin;
from 3.5% to 4.5% silver;
from 2.0% to 6% indium; and
from 0.3% to 1% copper.

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6. (Amended) A method of preparing a solder, comprising the steps of:
(a) mixing tin, silver, indium and copper to form the solder such that the proportion of tin in the solder is from 88.5% to 93.2%; the proportion of silver in the solder is from 3.5% to 4.5%; the proportion of indium in the solder is from 2.0% to 6%; and the proportion of copper in the solder is from 0.3% to 1.0%.

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11. (Amended) A method of soldering, comprising the steps of:
(a) forming a solder by combining tin, silver, indium and copper in the following proportions:
from 88.5% to 93.2% tin;
from 3.5% to 4.5% silver;
from 2.0% to 6.0% indium;
from 0.3% to 1.0% copper; and
(b) using the solder formed in step (a) to solder.

3. Remarks

The Examiner's careful evaluation of the application is appreciated. Each of the Examiner's comments, and each basis for rejection is addressed below.

a. The § 112 Rejections

The words "substantially lead free" have been removed from the preamble of claims 1, 6 and 11, thereby eliminating the basis for the indefiniteness rejection.